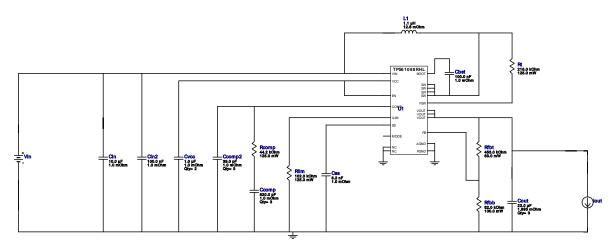


WEBENCH® Design Report

VinMin = 3.0V VinMax = 4.2V Vout = 10.0V lout = 2.5A Device = TPS61088RHLR Topology = Boost Created = 2019-07-23 07:09:14.061 BOM Cost = \$5.81 BOM Count = 22 Total Pd = 3.17W

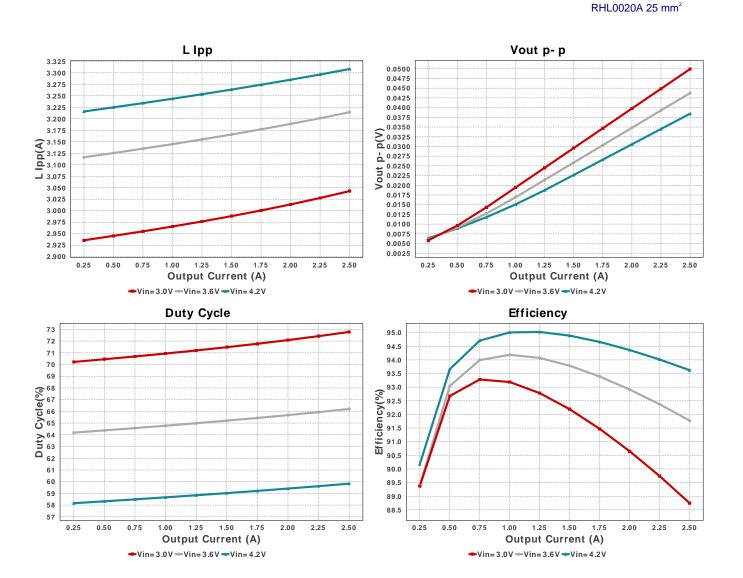
Design: 4 TPS61088RHLR TPS61088RHLR 3.6V-4.2V to 10.00V @ 2.8A

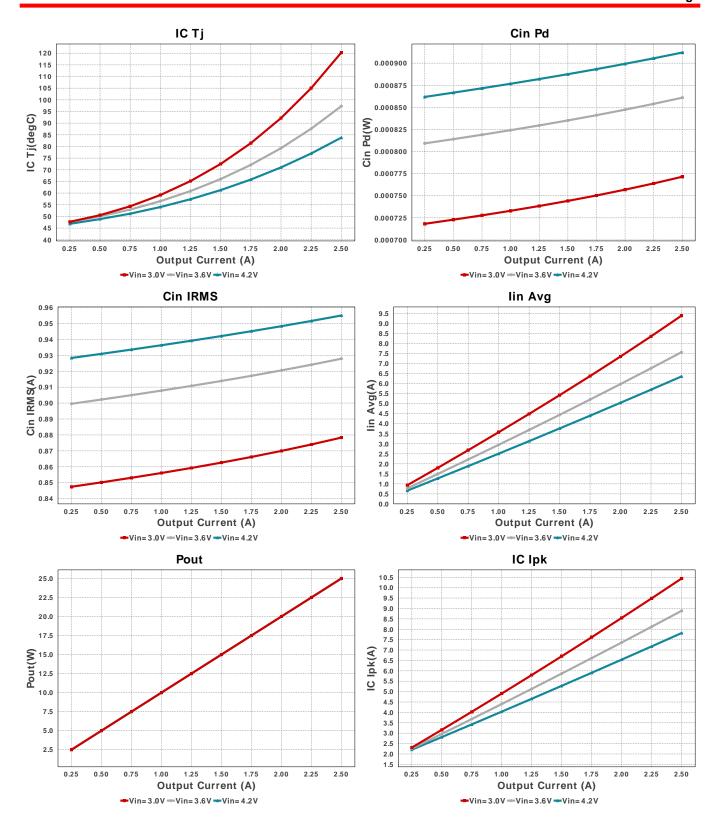


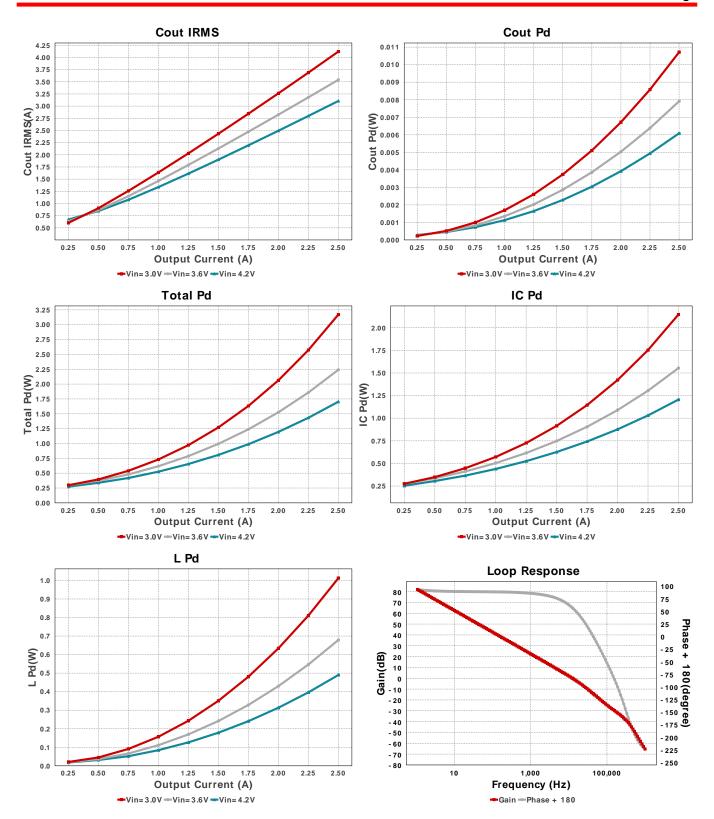
### **Electrical BOM**

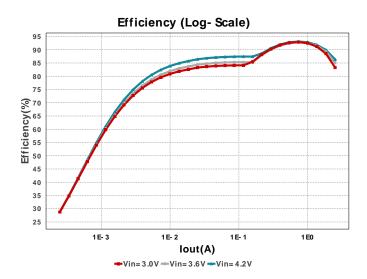
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbst	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm <sup>2</sup>
Ccomp	MuRata	GRM155R71H821KA01D Series= X7R	Cap= 820.0 pF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	3	\$0.01	0402 3 mm <sup>2</sup>
Ccomp2	MuRata	GRM1555C1E390JA01D Series= C0G/NP0	Cap= 39.0 pF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	3	\$0.01	0402 3 mm <sup>2</sup>
Cin	TDK	C3216X5R1H106K160AB Series= X5R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 4.9 A	1	\$0.30	1206_180 11 mm <sup>2</sup>
Cin2	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm <sup>2</sup>
Cout	TDK	CGA9P2X7R1E226M250KA Series= X7R	Cap= 22.0 uF ESR= 1.893 mOhm VDC= 25.0 V IRMS= 6.635 A	3	\$0.99	2220_280 54 mm <sup>2</sup>
Css	MuRata	GRM155R71C822KA01D Series= X7R	Cap= 8.2 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm <sup>2</sup>
Cvcc	Taiyo Yuden	EMK107B7105KA-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	2	\$0.02	0603 5 mm <sup>2</sup>
L1	Coilcraft	XAL6020-112MEB	L= 1.1 μH 12.6 mOhm	1	\$0.76	
						XAL6020 75 mm <sup>2</sup>

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rcomp	Vishay-Dale	CRCW080544K2FKEA Series= CRCWe3	Res= 44.2 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	0805 7 mm <sup>2</sup>
Rfbb	Yageo	RC0603FR-0762KL Series= ?	Res= 62.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
Rfbt	Vishay-Dale	CRCW0402453KFKED Series= CRCWe3	Res= 453.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rlim	Vishay-Dale	CRCW0805102KFKEA Series= CRCWe3	Res= 102.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	■ 0805 7 mm <sup>2</sup>
Rt	Panasonic	ERJ-6ENF2153V Series= ERJ-6E	Res= 215.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	■ 0805 7 mm <sup>2</sup>
U1	Texas Instruments	TPS61088RHLR	Switcher	1	\$1.60	









# **Operating Values**

•	raining valuoo			
#	Name	Value	Category	Description
1.	BOM Count	22		Total Design BOM count
2.	Total BOM	\$5.81		Total BOM Cost
3.	Cin IRMS	878.336 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	771.47 μW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	4.121 A	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	10.714 mW	Capacitor	Output capacitor power dissipation
7.	IC lpk	10.444 A	IC	Peak switch current in IC
8.	IC Pd	2.146 W	IC	IC power dissipation
9.	IC Ti	120.282 degC	IC	IC junction temperature
10.	ICThetaJA	38.8 degC/W	IC	IC junction-to-ambient thermal resistance
11.	lin Avg	9.39 A	IC	Average input current
12.	L lpp	3.043 A	Inductor	Peak-to-peak inductor ripple current
	L Pd	1.013 W	Inductor	Inductor power dissipation
	Cin Pd	771.47 μW	Power	Input capacitor power dissipation
	Cout Pd	10.714 mW	Power	Output capacitor power dissipation
	IC Pd	2.146 W	Power	· · · · · · · · · · · · · · · · · · · ·
		-		IC power dissipation
	L Pd	1.013 W	Power	Inductor power dissipation
	Total Pd	3.171 W	Power	Total Power Dissipation
19.	Cross Freq	12.167 kHz	System	Bode plot crossover frequency
			Information	
20.	Duty Cycle	72.779 %	System	Duty cycle
			Information	
21.	Efficiency	88.744 %	System	Steady state efficiency
			Information	
22.	FootPrint	337.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
			Information	
23.	Frequency	652.351 kHz	System	Switching frequency
			Information	
24.	Gain Marg	-14.258 dB	System	Bode Plot Gain Margin
			Information	
25.	lout	2.5 A	System	lout operating point
			Information	
26.	Low Freq Gain	80.59 dB	System	Gain at 1Hz
			Information	
27.	Mode	BOOST CCM	System	PWM/PFM Mode
			Information	
28.	Phase Marg	58.922 deg	System	Bode Plot Phase Margin
	Ü	J	Information	<b>G</b>
29.	Pout	25.0 W	System	Total output power
_			Information	
30.	Vin	3.0 V	System	Vin operating point
	•	0.0 .	Information	r in operating point
31.	Vout Actual	10.001 V	System	Vout Actual calculated based on selected voltage divider resistors
01.	vout / totaai	13.001 V	Information	Tour Adda darbuicted baded on delected vertage divider resistors
32.	Vout Tolerance	4.44 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider
JZ.	vout rolelance	<del>1.44</del> /0	Information	resistors if applicable
22	Vout n. n.	40.027 ~\/		''
33.	Vout p-p	49.937 mV	System	Peak-to-peak output ripple voltage
			Information	

# **Design Inputs**

Name	Value	Description	
lout	2.5	Maximum Output Current	
VinMax	4.2	Maximum input voltage	
VinMin	3.0	Minimum input voltage	
Vout	10.0	Output Voltage	
base_pn	TPS61088	Base Product Number	
source	DC	Input Source Type	
Та	37.0	Ambient temperature	

### WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

#### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 3.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

#### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



#### **Design Assistance**

- 1. Master key: 84F8F281898B6F10[v1]
- 2. TPS61088 Product Folder: http://www.ti.com/product/TPS61088: contains the data sheet and other resources.

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